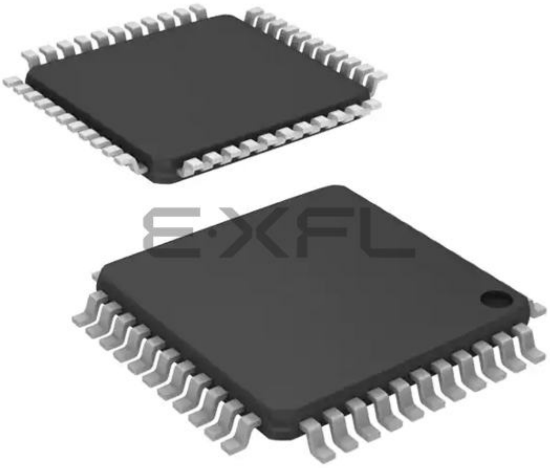
Microchip Technology - PIC24EP128MC204-H/PT Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep128mc204-h-pt

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes, and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

Ensure that the “Communication Channel Select” (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® PICkit™ 3, MPLAB ICD 3, or MPLAB REAL ICE™.

For more information on MPLAB ICD 2, ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

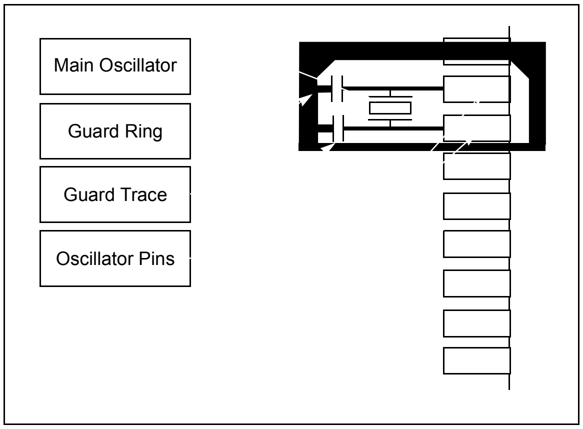
- *“Using MPLAB® ICD 3”* (poster) DS51765
- *“MPLAB® ICD 3 Design Advisory”* DS51764
- *“MPLAB® REAL ICE™ In-Circuit Emulator User’s Guide”* DS51616
- *“Using MPLAB® REAL ICE™ In-Circuit Emulator”* (poster) DS51749

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency Primary Oscillator and a low-frequency Secondary Oscillator. For details, see **Section 9.0 “Oscillator Configuration”** for details.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



4.4 Special Function Register Maps

TABLE 4-1: CPU CORE REGISTER MAP FOR dsPIC33EPXXXMC20X/50X AND dsPIC33EPXXXGP50X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
W0	0000	W0 (WREG)																xxxx
W1	0002	W1																xxxx
W2	0004	W2																xxxx
W3	0006	W3																xxxx
W4	0008	W4																xxxx
W5	000A	W5																xxxx
W6	000C	W6																xxxx
W7	000E	W7																xxxx
W8	0010	W8																xxxx
W9	0012	W9																xxxx
W10	0014	W10																xxxx
W11	0016	W11																xxxx
W12	0018	W12																xxxx
W13	001A	W13																xxxx
W14	001C	W14																xxxx
W15	001E	W15																xxxx
SPLIM	0020	SPLIM																0000
ACCAL	0022	ACCAL																0000
ACCAH	0024	ACCAH																0000
ACCAU	0026	Sign Extension of ACCA<39>								ACCAU								0000
ACCBL	0028	ACCBL																0000
ACCBH	002A	ACCBH																0000
ACCBU	002C	Sign Extension of ACCB<39>								ACCBU								0000
PCL	002E	PCL<15:0>															—	0000
PCH	0030	—	—	—	—	—	—	—	—	—	PCH<6:0>							0000
DSRPAG	0032	—	—	—	—	—	—	DSRPAG<9:0>										0001
DSWPAG	0034	—	—	—	—	—	—	—	DSWPAG<8:0>									0001
RCOUNT	0036	RCOUNT<15:0>																0000
DCOUNT	0038	DCOUNT<15:0>																0000
DOSTARTL	003A	DOSTARTL<15:1>															—	0000
DOSTARTH	003C	—	—	—	—	—	—	—	—	—	—	DOSTARTH<5:0>						0000
DOENDL	003E	DOENDL<15:1>															—	0000
DOENDH	0040	—	—	—	—	—	—	—	—	—	—	DOENDH<5:0>						0000

Legend: x = unknown value on Reset, — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

TABLE 4-24: CRC REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CRCCON1	0640	CRCEN	—	CSIDL	VWORD<4:0>					CRCFUL	CRCMPT	CRCISEL	CRCGO	LENDIAN	—	—	—	0000
CRCCON2	0642	—	—	—	DWIDTH<4:0>					—	—	—	PLEN<4:0>					0000
CRCXORL	0644	X<15:1>															—	0000
CRCXORH	0646	X<31:16>																0000
CRCDATL	0648	CRC Data Input Low Word																0000
CRCDATH	064A	CRC Data Input High Word																0000
CRCWDATL	064C	CRC Result Low Word																0000
CRCWDATH	064E	CRC Result High Word																0000

Legend: — = unimplemented, read as '0'. Shaded bits are not used in the operation of the programmable CRC module.

TABLE 4-25: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP FOR dsPIC33EPXXXGP/MC202/502 AND PIC24EPXXXGP/MC202 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPOR0	0680	—	—	RP35R<5:0>						—	—	RP20R<5:0>						0000
RPOR1	0682	—	—	RP37R<5:0>						—	—	RP36R<5:0>						0000
RPOR2	0684	—	—	RP39R<5:0>						—	—	RP38R<5:0>						0000
RPOR3	0686	—	—	RP41R<5:0>						—	—	RP40R<5:0>						0000
RPOR4	0688	—	—	RP43R<5:0>						—	—	RP42R<5:0>						0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-26: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP FOR dsPIC33EPXXXGP/MC203/503 AND PIC24EPXXXGP/MC203 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPOR0	0680	—	—	RP35R<5:0>						—	—	RP20R<5:0>						0000
RPOR1	0682	—	—	RP37R<5:0>						—	—	RP36R<5:0>						0000
RPOR2	0684	—	—	RP39R<5:0>						—	—	RP38R<5:0>						0000
RPOR3	0686	—	—	RP41R<5:0>						—	—	RP40R<5:0>						0000
RPOR4	0688	—	—	RP43R<5:0>						—	—	RP42R<5:0>						0000
RPOR5	068A	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
RPOR6	068C	—	—	—	—	—	—	—	—	—	—	RP56R<5:0>						0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-56: PORTA REGISTER MAP FOR PIC24EPXXXGP/MC203 AND dsPIC33EPXXXGP/MC203/503 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISA	0E00	—	—	—	—	—	—	—	TRISA8	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	011F
PORTA	0E02	—	—	—	—	—	—	—	RA8	—	—	—	RA4	RA3	RA2	RA1	RA0	0000
LATA	0E04	—	—	—	—	—	—	—	LATA8	—	—	—	LATA4	LATA3	LATA2	LA1TA1	LA0TA0	0000
ODCA	0E06	—	—	—	—	—	—	—	ODCA8	—	—	—	ODCA4	ODCA3	ODCA2	ODCA1	ODCA0	0000
CNENA	0E08	—	—	—	—	—	—	—	CNIEA8	—	—	—	CNIEA4	CNIEA3	CNIEA2	CNIEA1	CNIEA0	0000
CNPUA	0E0A	—	—	—	—	—	—	—	CNPUA8	—	—	—	CNPUA4	CNPUA3	CNPUA2	CNPUA1	CNPUA0	0000
CNPDA	0E0C	—	—	—	—	—	—	—	CNPDA8	—	—	—	CNPDA4	CNPDA3	CNPDA2	CNPDA1	CNPDA0	0000
ANSELA	0E0E	—	—	—	—	—	—	—	—	—	—	—	ANSA4	—	—	ANSA1	ANSA0	0013

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-57: PORTB REGISTER MAP FOR PIC24EPXXXGP/MC203 AND dsPIC33EPXXXGP/MC203/503 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISB	0E10	TRISB15	TRISB14	TRISB13	TRISB12	TRISB11	TRISB10	TRISB9	TRISB8	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	FFFF
PORTB	0E12	RB15	RB14	RB13	RB12	RB11	RB10	RB9	RB8	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx
LATB	0E14	LATB15	LATB14	LATB13	LATB12	LATB11	LATB10	LATB9	LATB8	LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	xxxx
ODCB	0E16	ODCB15	ODCB14	ODCB13	ODCB12	ODCB11	ODCB10	ODCB9	ODCB8	ODCB7	ODCB6	ODCB5	ODCB4	ODCB3	ODCB2	ODCB1	ODCB0	0000
CNENB	0E18	CNIEB15	CNIEB14	CNIEB13	CNIEB12	CNIEB11	CNIEB10	CNIEB9	CNIEB8	CNIEB7	CNIEB6	CNIEB5	CNIEB4	CNIEB3	CNIEB2	CNIEB1	CNIEB0	0000
CNPUB	0E1A	CNPUB15	CNPUB14	CNPUB13	CNPUB12	CNPUB11	CNPUB10	CNPUB9	CNPUB8	CNPUB7	CNPUB6	CNPUB5	CNPUB4	CNPUB3	CNPUB2	CNPUB1	CNPUB0	0000
CNPDB	0E1C	CNPDB15	CNPDB14	CNPDB13	CNPDB12	CNPDB11	CNPDB10	CNPDB9	CNPDB8	CNPDB7	CNPDB6	CNPDB5	CNPDB4	CNPDB3	CNPDB2	CNPDB1	CNPDB0	0000
ANSELB	0E1E	—	—	—	—	—	—	—	ANSB8	—	—	—	—	ANSB3	ANSB2	ANSB1	ANSB0	010F

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-58: PORTC REGISTER MAP FOR PIC24EPXXXGP/MC203 AND dsPIC33EPXXXGP/MC203/503 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISC	0E20	—	—	—	—	—	—	—	TRISC8	—	—	—	—	—	—	TRISC1	TRISC0	0103
PORTC	0E22	—	—	—	—	—	—	—	RC8	—	—	—	—	—	—	RC1	RC0	xxxx
LATC	0E24	—	—	—	—	—	—	—	LATC8	—	—	—	—	—	—	LATC1	LATC0	xxxx
ODCC	0E26	—	—	—	—	—	—	—	ODCC8	—	—	—	—	—	—	ODCC1	ODCC0	0000
CNENC	0E28	—	—	—	—	—	—	—	CNIEC8	—	—	—	—	—	—	CNIEC1	CNIEC0	0000
CNPUC	0E2A	—	—	—	—	—	—	—	CNPUC8	—	—	—	—	—	—	CNPUC1	CNPUC0	0000
CNPDC	0E2C	—	—	—	—	—	—	—	CNPDC8	—	—	—	—	—	—	CNPDC1	CNPDC0	0000
ANSELC	0E2E	—	—	—	—	—	—	—	—	—	—	—	—	—	—	ANSC1	ANSC0	0003

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.8.1 DATA ACCESS FROM PROGRAM MEMORY USING TABLE INSTRUCTIONS

The `TBLRDL` and `TBLWTL` instructions offer a direct method of reading or writing the lower word of any address within the Program Space without going through Data Space. The `TBLRDH` and `TBLWTH` instructions are the only method to read or write the upper 8 bits of a Program Space word as data.

The PC is incremented by two for each successive 24-bit program word. This allows program memory addresses to directly map to Data Space addresses. Program memory can thus be regarded as two 16-bit-wide word address spaces, residing side by side, each with the same address range. `TBLRDL` and `TBLWTL` access the space that contains the least significant data word. `TBLRDH` and `TBLWTH` access the space that contains the upper data byte.

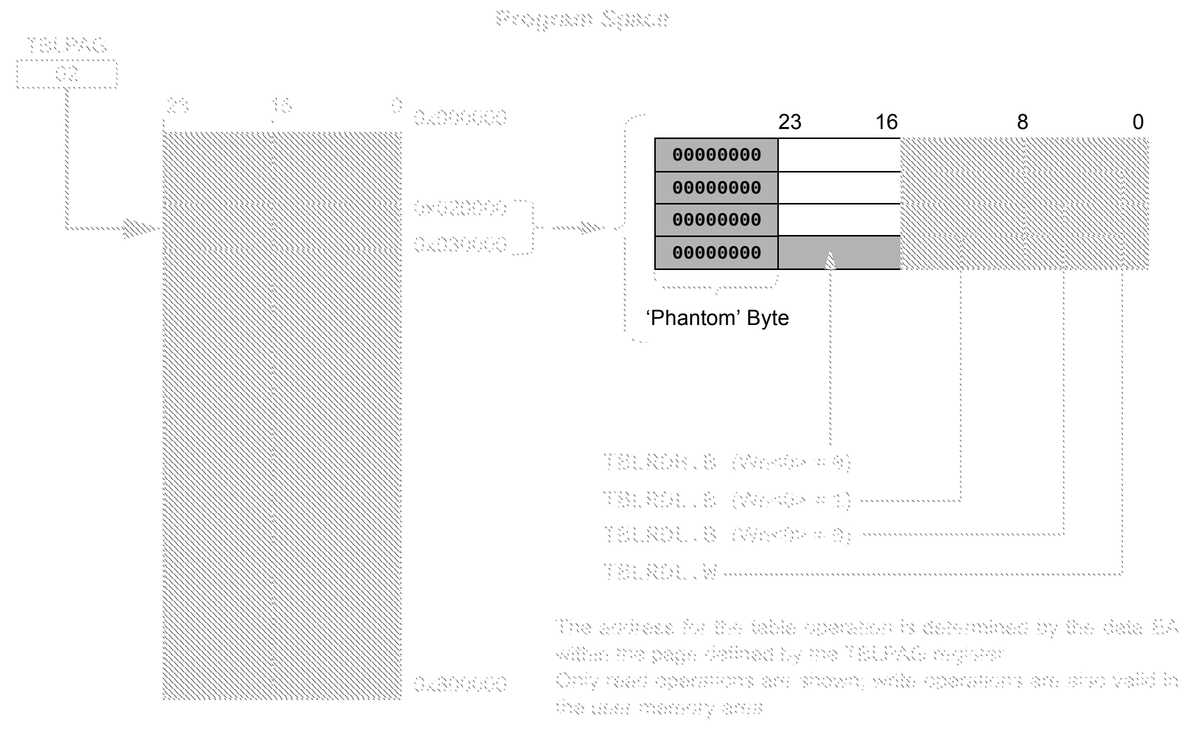
Two table instructions are provided to move byte or word-sized (16-bit) data to and from Program Space. Both function as either byte or word operations.

- `TBLRDL` (Table Read Low):
  - In Word mode, this instruction maps the lower word of the Program Space location (P<15:0>) to a data address (D<15:0>)
  - In Byte mode, either the upper or lower byte of the lower program word is mapped to the lower byte of a data address. The upper byte is selected when Byte Select is ‘`1`’; the lower byte is selected when it is ‘`0`’.
- `TBLRDH` (Table Read High):
  - In Word mode, this instruction maps the entire upper word of a program address (P<23:16>) to a data address. The ‘phantom’ byte (D<15:8>) is always ‘`0`’.
  - In Byte mode, this instruction maps the upper or lower byte of the program word to D<7:0> of the data address in the `TBLRDL` instruction. The data is always ‘`0`’ when the upper ‘phantom’ byte is selected (Byte Select = `1`).

In a similar fashion, two table instructions, `TBLWTH` and `TBLWTL`, are used to write individual bytes or words to a Program Space address. The details of their operation are explained in **Section 5.0 “Flash Program Memory”**.

For all table operations, the area of program memory space to be accessed is determined by the Table Page register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user application and configuration spaces. When TBLPAG<7> = `0`, the table page is located in the user memory space. When TBLPAG<7> = `1`, the page is located in configuration space.

FIGURE 4-23: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS



The address for the table operation is determined by the data EA within the page defined by the TBLPAG register.
Only read operations are shown; write operations are also valid in the user memory area.

REGISTER 9-1: OSCCON: OSCILLATOR CONTROL REGISTER(1) (CONTINUED)

bit 4	**Unimplemented:** Read as '`0`'
bit 3	**CF:** Clock Fail Detect bit(3) `1` = FSCM has detected clock failure `0` = FSCM has not detected clock failure
bit 2-1	**Unimplemented:** Read as '`0`'
bit 0	**OSWEN:** Oscillator Switch Enable bit `1` = Requests oscillator switch to selection specified by the NOSC<2:0> bits `0` = Oscillator switch is complete

Note 1: Writes to this register require an unlock sequence. Refer to **"Oscillator"** (DS70580) in the *"dsPIC33/PIC24 Family Reference Manual"* (available from the Microchip web site) for details.

2: Direct clock switches between any primary oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transitional clock source between the two PLL modes.

3: This bit should only be cleared in software. Setting the bit in software (= `1`) will have the same effect as an actual oscillator failure and trigger an oscillator failure trap.

TABLE 11-1: SELECTABLE INPUT SOURCES (MAPS INPUT TO FUNCTION)

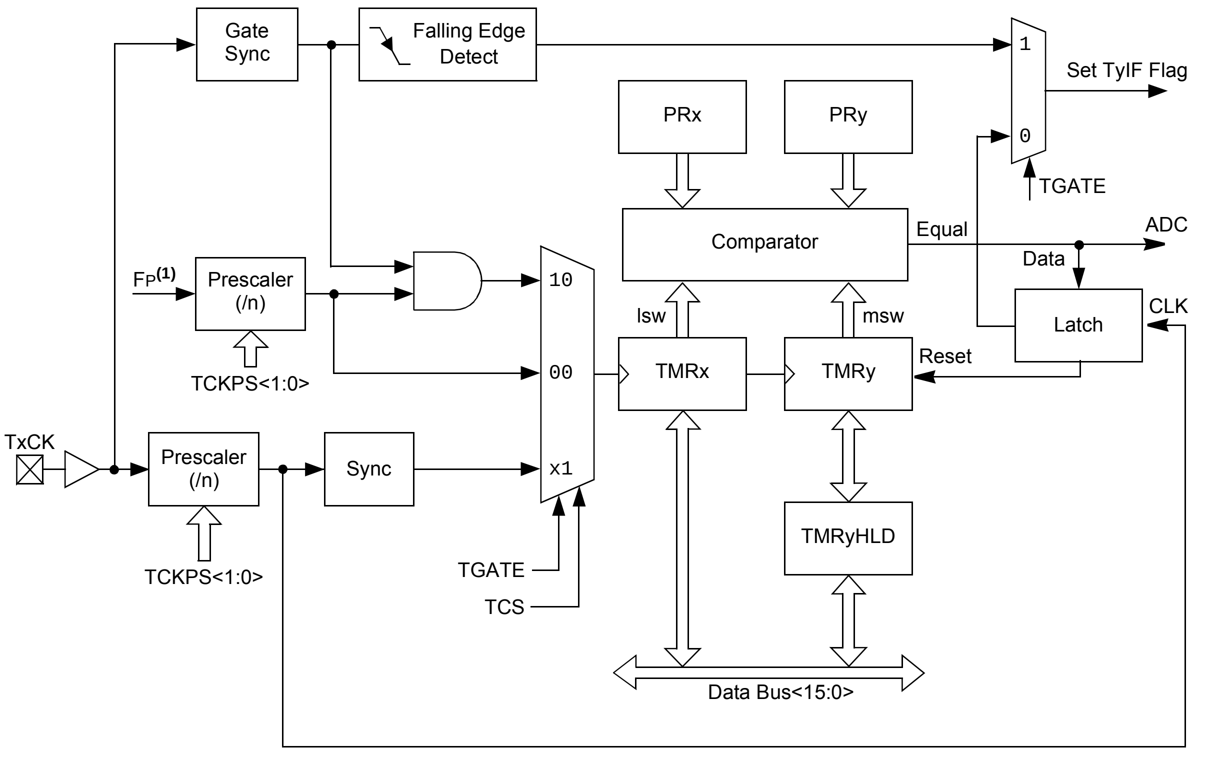
Input Name(1)	Function Name	Register	Configuration Bits
External Interrupt 1	INT1	RPINR0	INT1R<6:0>
External Interrupt 2	INT2	RPINR1	INT2R<6:0>
Timer2 External Clock	T2CK	RPINR3	T2CKR<6:0>
Input Capture 1	IC1	RPINR7	IC1R<6:0>
Input Capture 2	IC2	RPINR7	IC2R<6:0>
Input Capture 3	IC3	RPINR8	IC3R<6:0>
Input Capture 4	IC4	RPINR8	IC4R<6:0>
Output Compare Fault A	OCFA	RPINR11	OCFAR<6:0>
PWM Fault 1(3)	FLT1	RPINR12	FLT1R<6:0>
PWM Fault 2(3)	FLT2	RPINR12	FLT2R<6:0>
QEI1 Phase A(3)	QEA1	RPINR14	QEA1R<6:0>
QEI1 Phase B(3)	QEB1	RPINR14	QEB1R<6:0>
QEI1 Index(3)	INDX1	RPINR15	INDX1R<6:0>
QEI1 Home(3)	HOME1	RPINR15	HOM1R<6:0>
UART1 Receive	U1RX	RPINR18	U1RXR<6:0>
UART2 Receive	U2RX	RPINR19	U2RXR<6:0>
SPI2 Data Input	SDI2	RPINR22	SDI2R<6:0>
SPI2 Clock Input	SCK2	RPINR22	SCK2R<6:0>
SPI2 Slave Select	$\overline{\text{SS2}}$	RPINR23	SS2R<6:0>
CAN1 Receive(2)	C1RX	RPINR26	C1RXR<6:0>
PWM Sync Input 1(3)	SYNCI1	RPINR37	SYNCI1R<6:0>
PWM Dead-Time Compensation 1(3)	DTCMP1	RPINR38	DTCMP1R<6:0>
PWM Dead-Time Compensation 2(3)	DTCMP2	RPINR39	DTCMP2R<6:0>
PWM Dead-Time Compensation 3(3)	DTCMP3	RPINR39	DTCMP3R<6:0>

Note 1: Unless otherwise noted, all inputs use the Schmitt Trigger input buffers.

2: This input source is available on dsPIC33EPXXXGP/MC50X devices only.

3: This input source is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

FIGURE 13-3: TYPE B/TYPE C TIMER PAIR BLOCK DIAGRAM (32-BIT TIMER)



Note 1: The ADC trigger is available on the TMR3:TMR2 andTMR5:TMR4 32-bit timer pairs.

2: Timerx is a Type B timer (x = 2 and 4).

3: Timery is a Type C timer (y = 3 and 5).

13.1 Timerx/y Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser:
http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

13.1.1 KEY RESOURCES

- **“Timers”** (DS70362) in the *“dsPIC33/PIC24 Family Reference Manual”*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *“dsPIC33/PIC24 Family Reference Manual”* Sections
- Development Tools

16.0 HIGH-SPEED PWM MODULE (dsPIC33EPXXXMC20X/50X AND PIC24EPXXXMC20X DEVICES ONLY)

> **Note 1:** This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"High-Speed PWM"** (DS70645) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices support a dedicated Pulse-Width Modulation (PWM) module with up to 6 outputs.

The high-speed PWMx module consists of the following major features:

- Three PWM generators
- Two PWM outputs per PWM generator
- Individual period and duty cycle for each PWM pair
- Duty cycle, dead time, phase shift and frequency resolution of TCY/2 (7.14 ns at FCY = 70MHz)
- Independent Fault and current-limit inputs for six PWM outputs
- Redundant output
- Center-Aligned PWM mode
- Output override control
- Chop mode (also known as Gated mode)
- Special Event Trigger
- Prescaler for input clock
- PWMxL and PWMxH output pin swapping
- Independent PWM frequency, duty cycle and phase-shift changes for each PWM generator
- Dead-time compensation
- Enhanced Leading-Edge Blanking (LEB) functionality
- Frequency resolution enhancement
- PWM capture functionality

> **Note:** In Edge-Aligned PWM mode, the duty cycle, dead time, phase shift and frequency resolution are 8.32 ns.

The high-speed PWMx module contains up to three PWM generators. Each PWM generator provides two PWM outputs: PWMxH and PWMxL. The master time base generator provides a synchronous signal as a common time base to synchronize the various PWM outputs. The individual PWM outputs are available on the output pins of the device. The input Fault signals and current-limit signals, when enabled, can monitor and protect the system by placing the PWM outputs into a known "safe" state.

Each PWMx can generate a trigger to the ADC module to sample the analog signal at a specific instance during the PWM period. In addition, the high-speed PWMx module also generates a Special Event Trigger to the ADC module based on either of the two master time bases.

The high-speed PWMx module can synchronize itself with an external signal or can act as a synchronizing source to any external device. The SYNCI1 input pin that utilizes PPS, can synchronize the high-speed PWMx module with an external signal. The SYNCO1 pin is an output pin that provides a synchronous signal to an external device.

Figure 16-1 illustrates an architectural overview of the high-speed PWMx module and its interconnection with the CPU and other peripherals.

16.1 PWM Faults

The PWMx module incorporates multiple external Fault inputs to include FLT1 and FLT2 which are remappable using the PPS feature, FLT3 and FLT4 which are available only on the larger 44-pin and 64-pin packages, and FLT32 which has been implemented with Class B safety features, and is available on a fixed pin on all dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

These Faults provide a safe and reliable way to safely shut down the PWM outputs when the Fault input is asserted.

16.1.1 PWM FAULTS AT RESET

During any Reset event, the PWMx module maintains ownership of the Class B Fault, FLT32. At Reset, this Fault is enabled in Latched mode to ensure the fail-safe power-up of the application. The application software must clear the PWM Fault before enabling the high-speed motor control PWMx module. To clear the Fault condition, the FLT32 pin must first be pulled low externally or the internal pull-down resistor in the CNPDx register can be enabled.

> **Note:** The Fault mode may be changed using the FLTMOD<1:0> bits (FCLCON<1:0>), regardless of the state of FLT32.

REGISTER 16-1: PTCON: PWMx TIME BASE CONTROL REGISTER (CONTINUED)

bit 6-4	**SYNCSRC<2:0>:** Synchronous Source Selection bits(1) `111` = Reserved • • • `100` = Reserved `011` = PTGO17(2) `010` = PTGO16(2) `001` = Reserved `000` = SYNCI1 input from PPS
bit 3-0	**SEVTPS<3:0>:** PWMx Special Event Trigger Output Postscaler Select bits(1) `1111` = 1:16 Postscaler generates Special Event Trigger on every sixteenth compare match event • • • `0001` = 1:2 Postscaler generates Special Event Trigger on every second compare match event `0000` = 1:1 Postscaler generates Special Event Trigger on every compare match event

Note 1: These bits should be changed only when PTEN = `0`. In addition, when using the SYNCI1 feature, the user application must program the period register with a value that is slightly larger than the expected period of the external synchronization input signal.

2: See **Section 24.0 “Peripheral Trigger Generator (PTG) Module”** for information on this selection.

REGISTER 24-8: PTGC1LIM: PTG COUNTER 1 LIMIT REGISTER[1]

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGC1LIM<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGC1LIM<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0	**PTGC1LIM<15:0>:** PTG Counter 1 Limit Register bits May be used to specify the loop count for the `PTGJMPC1` Step command or as a limit register for the General Purpose Counter 1.

Note 1: This register is read-only when the PTG module is executing Step commands (PTGEN = `1` and PTGSTRT = `1`).

REGISTER 24-9: PTGHOLD: PTG HOLD REGISTER[1]

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGHOLD<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGHOLD<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0	**PTGHOLD<15:0>:** PTG General Purpose Hold Register bits Holds user-supplied data to be copied to the PTGTxLIM, PTGCxLIM, PTGSDLIM or PTGL0 registers with the `PTGCOPY` command.

Note 1: This register is read-only when the PTG module is executing Step commands (PTGEN = `1` and PTGSTRT = `1`).

TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended					
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**	
	I_{IL}	**Input Leakage Current**[1,2]						
DI50		I/O Pins 5V Tolerant[3]	-1	—	+1	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, Pin at high-impedance	
DI51		I/O Pins Not 5V Tolerant[3]	-1	—	+1	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, Pin at high-impedance, -40°C ≤ T_A ≤ +85°C	
DI51a		I/O Pins Not 5V Tolerant[3]	-1	—	+1	μA	Analog pins shared with external reference pins, -40°C ≤ T_A ≤ +85°C	
DI51b		I/O Pins Not 5V Tolerant[3]	-1	—	+1	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, Pin at high-impedance, -40°C ≤ T_A ≤ +125°C	
DI51c		I/O Pins Not 5V Tolerant[3]	-1	—	+1	μA	Analog pins shared with external reference pins, -40°C ≤ T_A ≤ +125°C	
DI55		$\overline{\text{MCLR}}$	-5	—	+5	μA	$V_{SS} \le V_{PIN} \le V_{DD}$	
DI56		OSC1	-5	—	+5	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, XT and HS modes	

Note 1: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

2: Negative current is defined as current sourced by the pin.

3: See the **"Pin Diagrams"** section for the 5V tolerant I/O pins.

4: V_{IL} source < (V_{SS} – 0.3). Characterized but not tested.

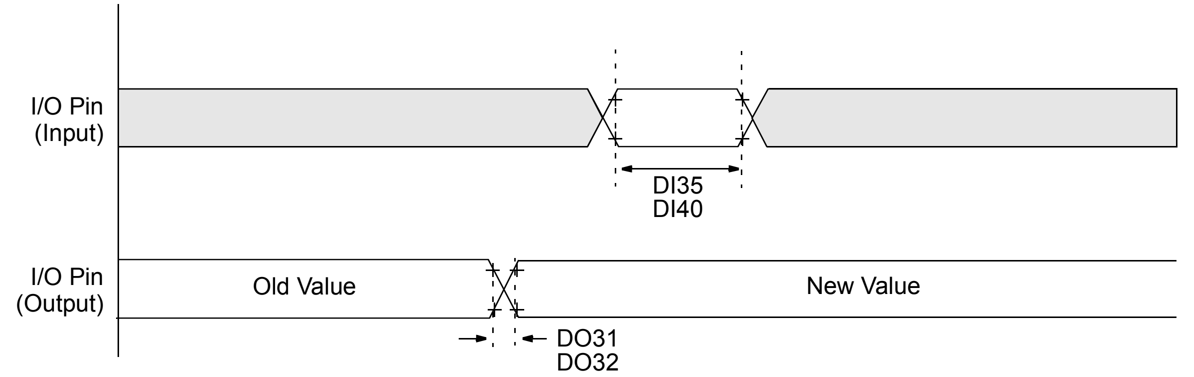
5: Non-5V tolerant pins V_{IH} source > (V_{DD} + 0.3), 5V tolerant pins V_{IH} source > 5.5V. Characterized but not tested.

6: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

7: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

8: Any number and/or combination of I/O pins not excluded under I_{ICL} or I_{ICH} conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

FIGURE 30-3: I/O TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-21: I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.[(1)]**	**Max.**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	5	10	ns	
DO32	TIOF	Port Output Fall Time	—	5	10	ns	
DI35	TINP	INTx Pin High or Low Time (input)	20	—	—	ns	
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TCY	

Note 1: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

FIGURE 30-4: BOR AND MASTER CLEAR RESET TIMING CHARACTERISTICS

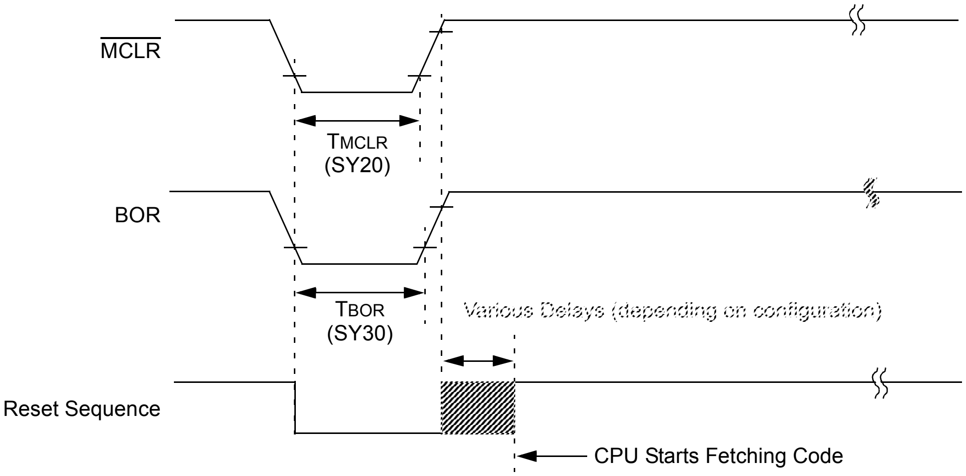
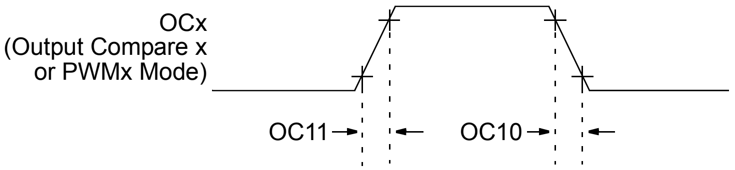


FIGURE 30-7: OUTPUT COMPARE x MODULE (OCx) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-27: OUTPUT COMPARE x MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
OC10	TccF	OCx Output Fall Time	—	—	—	ns	See Parameter DO32
OC11	TccR	OCx Output Rise Time	—	—	—	ns	See Parameter DO31

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 30-8: OCx/PWMx MODULE TIMING CHARACTERISTICS

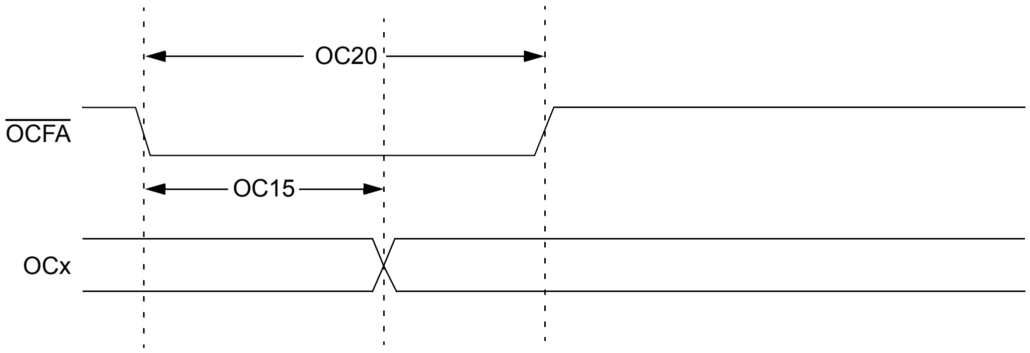


TABLE 30-28: OCx/PWMx MODE TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
OC15	TFD	Fault Input to PWMx I/O Change	—	—	TCY + 20	ns	
OC20	TFLT	Fault Input Pulse Width	TCY + 20	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

TABLE 30-37: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK2 Input Frequency	—	—	Lesser of FP or 15	MHz	**(Note 3)**
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SS2}}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SS2}}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{\text{SS2}}$ ↑ after SCK2 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**
SP60	TssL2doV	SDO2 Data Output Valid after $\overline{\text{SS2}}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 66.7 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

TABLE 30-48: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = `0`, CKP = `0`, SMP = `0`) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK1 Input Frequency	—	—	11	MHz	**(Note 3)**
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SS1}}$ ↓ to SCK1 ↑ or SCK1 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SS1}}$ ↑ to SDO1 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH, TscL2ssH	$\overline{\text{SS1}}$ ↑ after SCK1 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

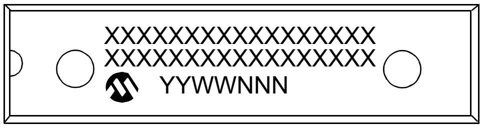
3: The minimum clock period for SCK1 is 91 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

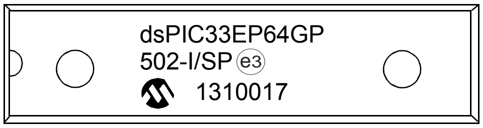
33.0 PACKAGING INFORMATION

33.1 Package Marking Information

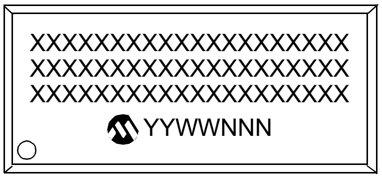
28-Lead SPDIP



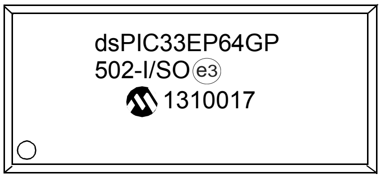
Example



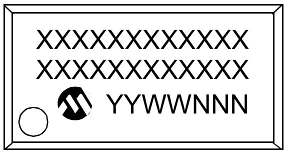
28-Lead SOIC (.300”)



Example

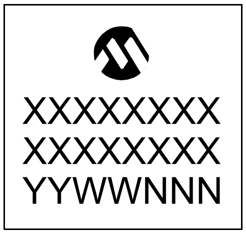


28-Lead SSOP



Example

28-Lead QFN-S (6x6x0.9 mm)



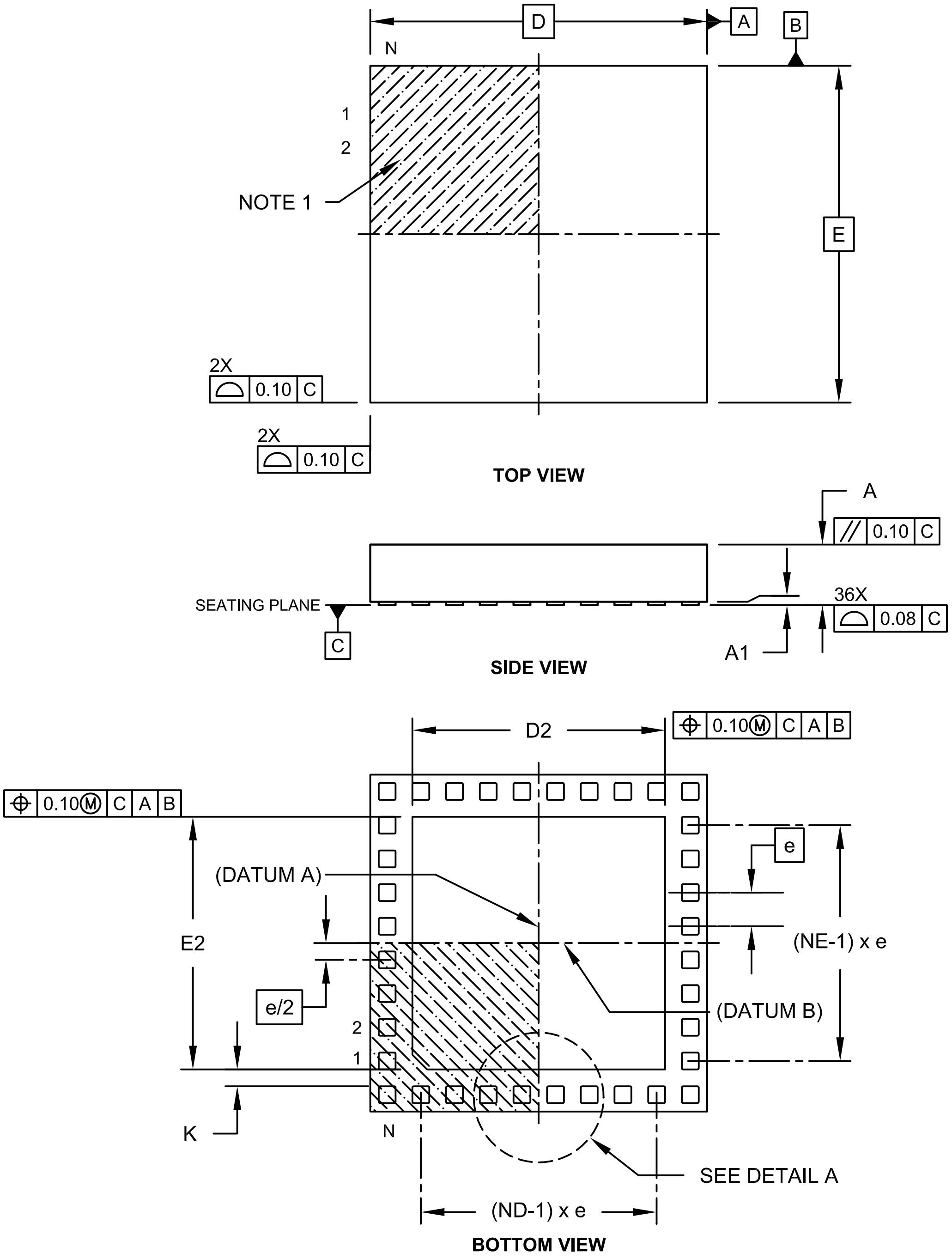
Example

Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	e3	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



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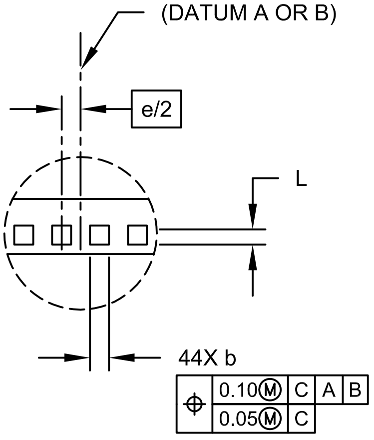
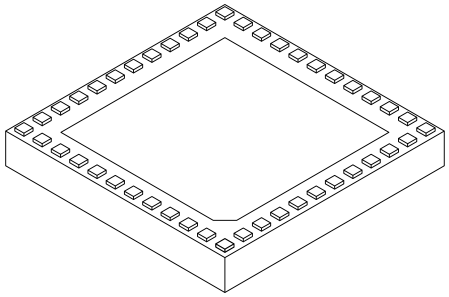
44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body With Exposed Pad [VTLA]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



DETAIL A



	Units	MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Pins	N		44	
Number of Pins per Side	ND		12	
Number of Pins per Side	NE		10	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.025	-	0.075
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	4.40	4.55	4.70
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	4.40	4.55	4.70
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-157C Sheet 2 of 2

NOTES: